

PCB SPECIFICATIONS :

A. MATERIAL :

☒FR-4☐TG-170☐TG-150☐TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☒BLUE☐WHITE☐RED☐BLACK

D. SILKSCREEN COLOR :

☒WHITE☐YELLOW☐BLACK☐Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ENIG☐IMMERSION SILVER☐IMMERSION TIN☐HASL☐HASL (PB-FREE)☐GOLDEN FINGER

F. IMPEDANCE CONTROL :

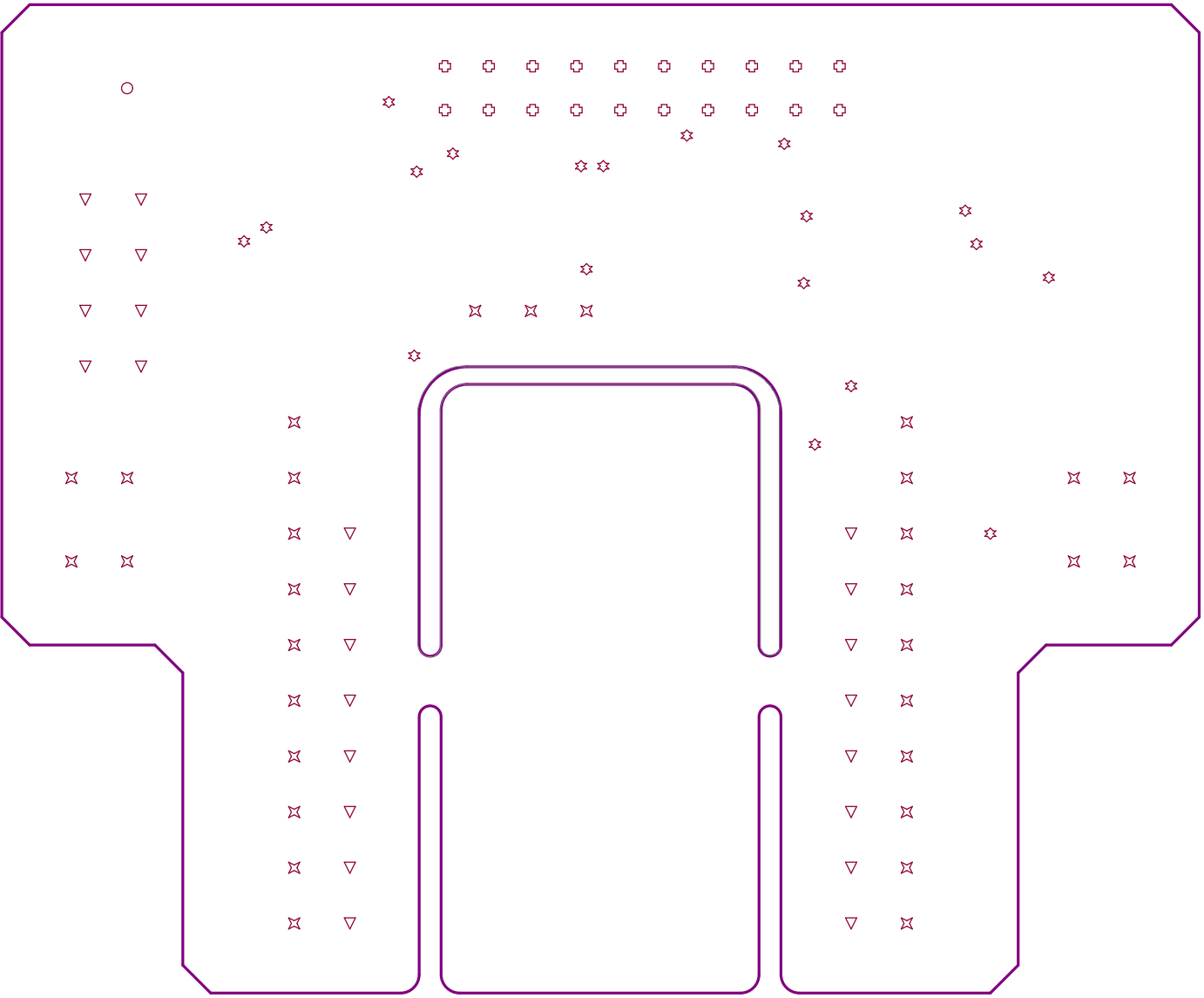
☒NO☐YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒SOLDERMASK☐NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
○	1	157.48mil (4.00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c500h400m0mx0				-	-
✳	19	8.00mil (0.20mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v41h20m0mx0				-	-
⊕	20	35.43mil (0.90mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
▽	24	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
✳	31	39.37mil (1.00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
	95 Total												

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.05mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				